

Ormet Circuits

Product Line Overview

Application	Product	Lead Free	Process	Viscosity	Thermal Conductivity	Cure
Via Fill & Z-axis Interconnection	Ormet 701 A copper-based conductive paste used to form Z-axis interconnects by filling microvias in multilayer boards and substrates	Yes	Screen Print / Dispense	200-300 KCPS	25 W/mK	Lamination Press Autoclave Vacuum Bag
	Ormet 701AG A silver-based conductive paste used to form Z-axis interconnects by filling microvias in multilayer boards and substrates	Yes	Screen Print / Dispense	200-300 KCPS	25 W/mK	Lamination Press Autoclave Vacuum Bag
	Ormet 7001 A lead-based conductive paste used to form Z-axis interconnects by filling microvias in multilayer boards and substrates	No	Screen Print / Dispense	200-300 KCPS	25 W/mK	Lamination Press Autoclave Vacuum Bag
Die Attach	Ormet 555: A copper-based dispensable, or screen printable, electrically and thermally conductive paste for discrete, IC, and LED die attach applications.	Yes	Screen Print / Dispense	100-300 KCPS	25 W/mK	Box Oven with Nitrogen Atmosphere
	Ormet 580 A silver-based dispensable, or screen printable, electrically and thermally conductive paste for discrete, IC, and LED die attach applications.	Yes	Screen Print / Dispense	100-300 KCPS	25 W/mK	Box Oven with Nitrogen Atmosphere
Conductive lines and traces	Ormet 260 A screen printable, electrically conductive paste used for signal circuit creation and jumper wire repair.	Yes	Screen Print / Dispense	150-300 KCPS	25 W/mK	Reflow or Box Oven with Nitrogen Atmosphere
	Ormet 260C A dispensable or screen printable, <i>non slumping</i> , electrically conductive paste used for creating conductive lines down to 80 microns.	Yes	Screen Print / Dispense	200-300 KCPS	25 W/mK	Reflow or Box Oven with Nitrogen Atmosphere
	Ormet 2600 A lead based screen printable, electrically conductive paste used for signal circuit creation and jumper wire repair.	No	Screen Print / Dispense	150-300 KCPS	25 W/mK	Reflow or Box Oven with Nitrogen Atmosphere
Solder Replacement	Ormet 400 A screen printable conductive paste used as an alternative to solder paste.	Yes	Screen Print / Dispense	100-300 KCPS	25 W/mK	Reflow or Box Oven with Nitrogen Atmosphere
PTH fill	Ormet 802 A conductive paste used for plugging thermal vias and copper through holes.	Yes	Pneumatic Pressure Fill	400-600 KCPS	58 W/mK	Lamination Press Autoclave Vacuum Bag